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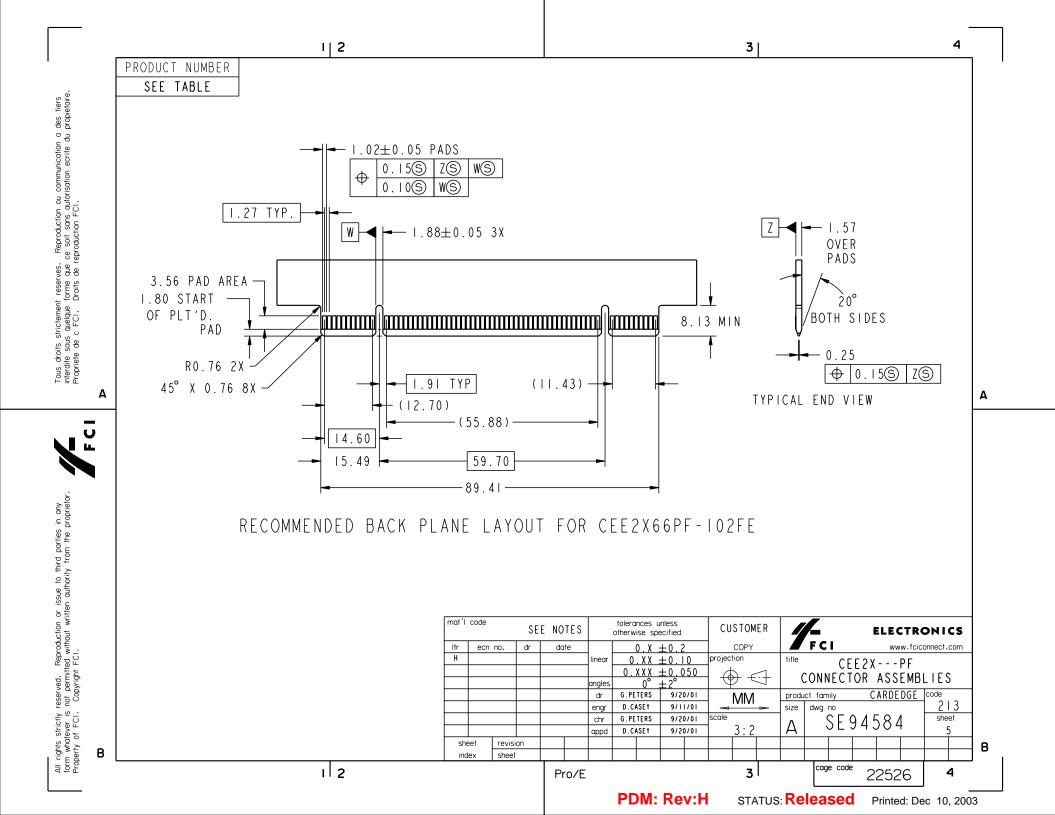
PDM: Rev:H

STATUS: Released Printed: Dec 10, 2003

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NOTES:

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- INTERPRET THIS DRAWING IN ACOCRDANCE WITH ANSI YI4.5M -1982.
- CONNECTORS WITH CARD COLLECTING SCOOPS ARE DESIGNED TO ACCOMMODATE 1.57+/-.180 PC BOARDS WITH WARPAGE UP TO +/-2.03.

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- RECOMMENDED COMPONENT BOARD MATERIAL: P.C. BOARD: FR-4 WITH 28.35 GRAMS MIN. COPPER, PADS PLATED WITH .76 MICRONS MIN GOLD, PER MIL-G-45204, TYPE I, CLASS I, GRADE C OVER 2.54 MICRONS MIN NI. UNDERPLPATE PER QQ-N-290.
- RECOMMENDED BACK PLANE THICKNESS IS 2.39 FOR 3.71 COMPLIANTTAIL.
- CONTACT MATING SURFACES ARE LUBRICATED WITH OS-138.
- MATERIAL:

BODY: POLYPHENYLENE SULFIDE(PPS) UL RATED 94V-0 COLOR, BROWN

CONTACTS: PHOS BRONZE, PER FCI SPEC. M738

CONTACT FINISH: FE 0.75 MICRONS MIN GOLD IN CONTACT AREA 1-3 MICRONS MIN TIN LEAD ON SOLDER TAILS 2 MICRONS MIN NI UNDERPLATE ALL OVER.

- PERFORMANCE CHARACTERISTICS: SEE SHEET 7.
- APPLICATION SPECIFICATION PER BUS-09-026.
- ITEM NAME, LOGO, PART NUMBER, DATE CODE, AND UL SYMBOLS TO APPEAR IN THIS AREA.

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SEE TABLE

PERFORMANCE CHARACTERISTICS:

FNVIRONMENTAL:

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OPERTATING TMEPERATURE: -40C TO 105C

THERMAL SHOCK: MIL-STD-1344. METHOD 1003.1)-55C TO +85C. 5 CYCLES)

FLAMABILITY RATING: UL94V-0

MECHANICAL:

DURABILITY: 100 MATING CYCLES WITHOUT PHYSICAL DAMAGE, OR EXCEEDING LOW LEVEL CONTACT

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RESISTANCE REQUIREMENTS WHEN MATED WITH RECOMMENDED CARD.

CONTACT RETENTION: MIL-STD-1344, METHOD 2007.1, 4.4 N MIN.

MATING FORCE: MIL-STD-1344, MEHTOD 2013.1 2.0 N MAX. AVERAGE PER OPPOSING PAIR USING

GAUGE PER MIL-STD-C-21097 WITH CARD PROFILE

CONTACT NORMAL FORCE: 0.72 N MINIMUM

PRESS FIT TERMINATION FORCES: INSERTION FORCE 70 N MAX. PER PIN

RETENTION FORCE 9 N MIN. PER PIN

ELECTRICAL:

CONTACT RESISTANCE: MIL-STD-1344, METHOD 3002-1, WITH 10 MILLIOHM MAX. INITIAL, 20 (LOW SIGNAL LEVEL) MILLIOHM RISE. COMPONENT BOARD SIDE - I MILLIOHM MAX., CONNECTION

PRESS FIT PIN WITH W/PLATED THROUGH HOLE.

INSULATION RESISTANCE: MILL-STD-202, METHOD 302, CONDITION B, 1000 MEGAOHMS MIN.

DIELECTRIC WITHSTAND VOLTAGE: MIL-STD-1344, METHOD D3001.1 CONDITION 1, 500 VAC RM

CAPACITANCE: 2 PICROFARADS, MAX AT I MEGAHERTZ

CURRENT RATING: I AMP, 30C RISE ABOVE AMBIENT

VOLTAGE RATING: 150 VAC (RMS)

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